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Problems | Problèmes

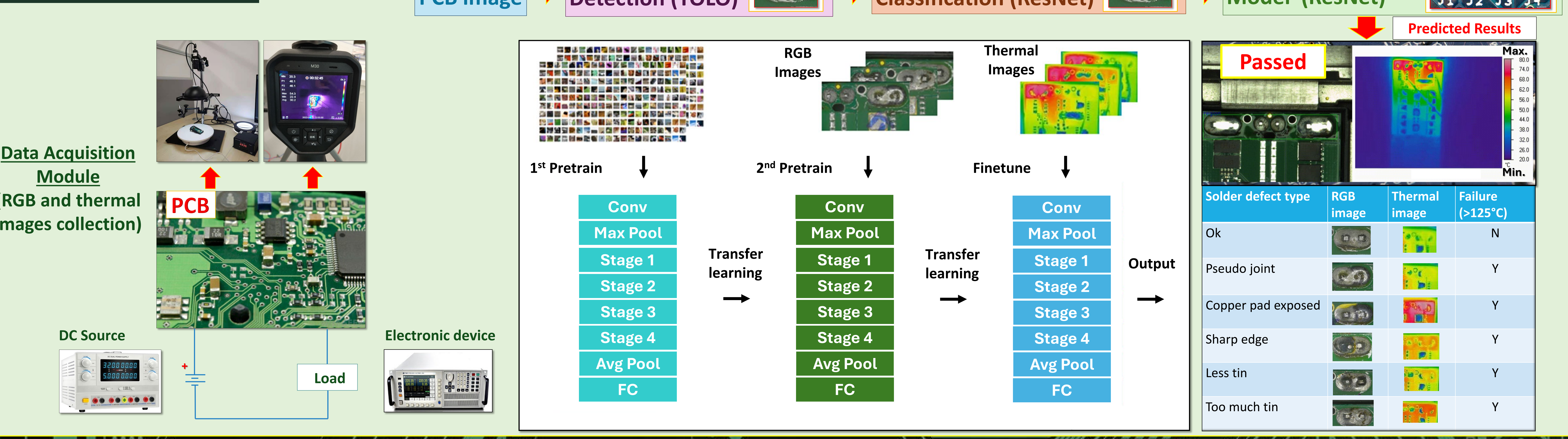
- More than 60% of electronic product failures are attributed to solder joint failures
- Lack of early detection of solder joint failure mechanisms on the production line of printed circuit boards (PCB)
- The current method relies on manual inspection, which has limited accuracy and wastes manpower



CAiRS Solution, Novelty and Impact | Solution CAiRS, nouveauté et impact

- **Solution:** AI-Based PCB Soldering Failure Mechanism Prediction System
- **Novelty:** Integration of advanced deep learning models to identify PCB solder joints, classify defects, and predict failure mechanisms
- **Impact:** (1) Reduction in Manual Quality Checks, (2) Early Detection of Solder Joint Defects, (3) Cost-Effective Solution.

The Invention



Applications

- PCB Solder Joints Failure Prediction in
- Household appliances
 - Medical devices
 - Mechanical engineering products
 - Consumer electronics

The Achieved Outcomes | Les résultats obtenus

- ✓ Model accuracy > 85%
- ✓ Reduced device malfunctions by more than 25% (soldering quality issues)
- ✓ Save > a reduction percentage by more than 30% in manpower cost

Patent/ Brevet

Title: AI-Based Failure Mechanism Prediction System and Method for PCB Solder Joints
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